

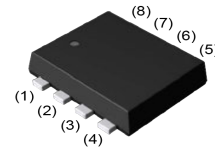
Features

- N Channel (Integrated Schottky Diode)**
 30V/7A,
 $R_{DS(ON)} = 22m\Omega$ (typ.) @ $V_{GS} = 10V$
 $R_{DS(ON)} = 35m\Omega$ (typ.) @ $V_{GS} = 4.5V$
- P Channel**
 -30V/-5.5A,
 $R_{DS(ON)} = 37m\Omega$ (typ.) @ $V_{GS} = -10V$
 $R_{DS(ON)} = 55m\Omega$ (typ.) @ $V_{GS} = -4.5V$
- 100% UIS + R_g Tested
- Reliable and Rugged
- Lead Free Available (RoHS Compliant)

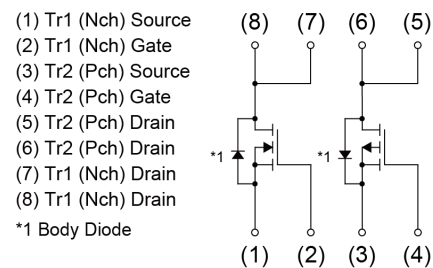
Applications

- Synchronous Rectification.
- Motor Control.
- Fan Application.

Pin Description



Top View of TSMT8



Absolute Maximum Ratings (T_A = 25°C unless otherwise noted)

Symbol	Parameter		N Channel	P Channel	Unit
Common Ratings					
V _{DSS}	Drain-Source Voltage		30	-30	V
V _{GSS}	Gate-Source Voltage		±20	±20	
T _J	Maximum Junction Temperature		150		°C
T _{STG}	Storage Temperature Range		-55 to 150		
I _S	Diode Continuous Forward Current	T _A =25°C	7	-5.5	A
I _D	Continuous Drain Current	T _A =25°C	7	-5.5	
I _{DM} ^a	Pulsed Drain Current	T _A =25°C	21	-16.5	
P _D	Power Dissipation	T _A =25°C	2 ^d	2 ^d	W
		T _A =70°C	1.3 ^d	1.3 ^d	
R _{θJA}	Thermal Resistance-Junction to Ambient	t ≤ 10s	60	60	°C/W
		Steady State ^b	90	90	
I _{AS} ^c	Avalanche Current, Single pulse	L=0.1mH	13	16	A
E _{AS} ^c	Avalanche Energy, Single pulse	L=0.1mH	8	13	mJ

Note a : Pulse width limited by max. junction temperature.

Note b : R_{θJA} steady state t=100s. R_{θJA} is measured with the device mounted on 1in² · FR-4 board with 2oz. Copper.

Note c : UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature T_J=25°C).

Note d : t < 10s.

N Channel Electrical Characteristics (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	N Channel			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =24V, V _{GS} =0V	-	-	1	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250μA	1.2	1.7	2.2	V
I _{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
R _{DS(ON)} ^e	Drain-Source On-state Resistance	V _{GS} = 10V, I _{DS} =4A	-	22	29	mΩ
		V _{GS} =4.5V, I _{DS} =4A	-	35	46	
Diode Characteristics						
V _{SD} ^e	Diode Forward Voltage	I _{SD} =1A, V _{GS} =0V	-	0.41	0.6	V
t _{rr}	Reverse Recovery Time	I _{SD} =4A, dI _{SD} /dt=100A/μs	-	9.8	-	ns
Q _{rr}	Reverse Recovery Charge		-	3	-	nC
Dynamic Characteristics ^f						
R _G	Gate Resistance	V _{GS} =0V,V _{DS} =0V,F=1MHz	-	2.7	-	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =15V, Frequency=1.0MHz	-	405	-	pF
C _{oss}	Output Capacitance		-	105	-	
C _{rss}	Reverse Transfer Capacitance		-	45	-	
t _{d(ON)}	Turn-on Delay Time	V _{DD} = 15V, R _L =15Ω, I _{DS} =1A, V _{GEN} =10V, R _G =6Ω	-	5.2	-	ns
t _r	Turn-on Rise Time		-	10.2	-	
t _{d(OFF)}	Turn-off Delay Time		-	15.2	-	
t _f	Turn-off Fall Time		-	3.6	-	
Gate Charge Characteristics ^f						
Q _g	Total Gate Charge	V _{DS} =15V, V _{GS} =4.5V, I _{DS} =4A	-	4.2	-	nC
Q _g	Total Gate Charge	V _{DS} =15V, V _{GS} =10V, I _{DS} =4A	-	8.82	-	
Q _{gs}	Gate-Source Charge		-	1.69	-	
Q _{gd}	Gate-Drain Charge		-	1.56	-	
Q _{gth}	Threshold Gate Charge		-	0.78	-	

Note e : Pulse test ; pulse width≤300μs, duty cycle≤2%.

Note f : Guaranteed by design, not subject to production testing.

:

P Channel Electrical Characteristics (T_A = 25°C unless otherwise noted)

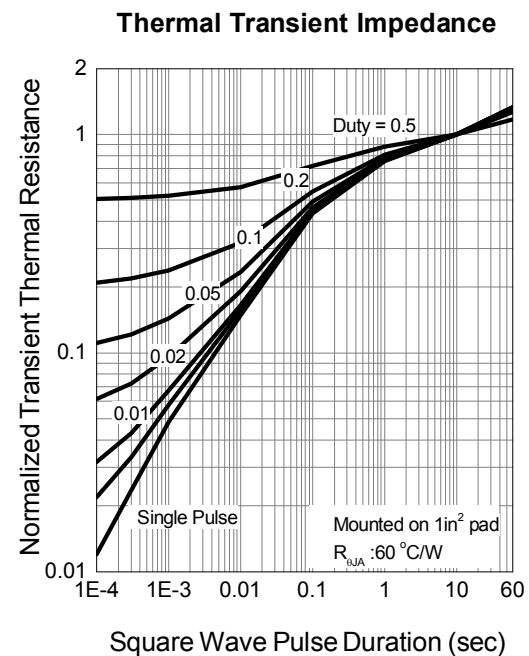
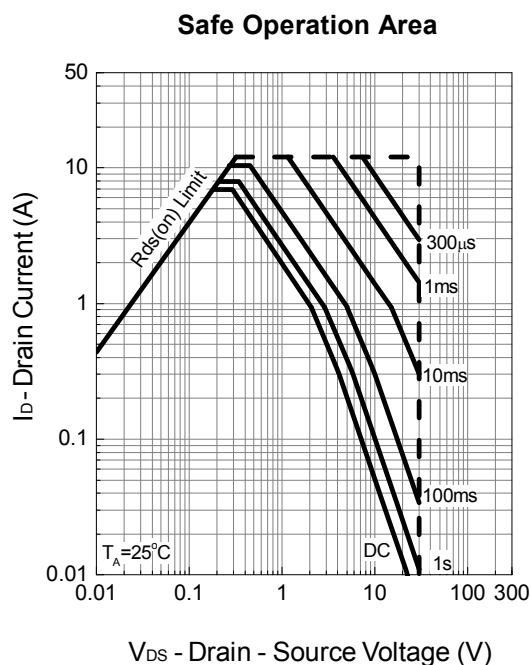
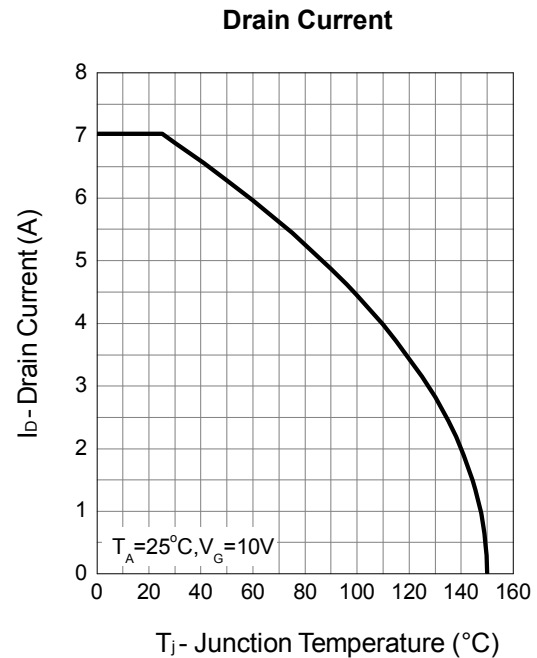
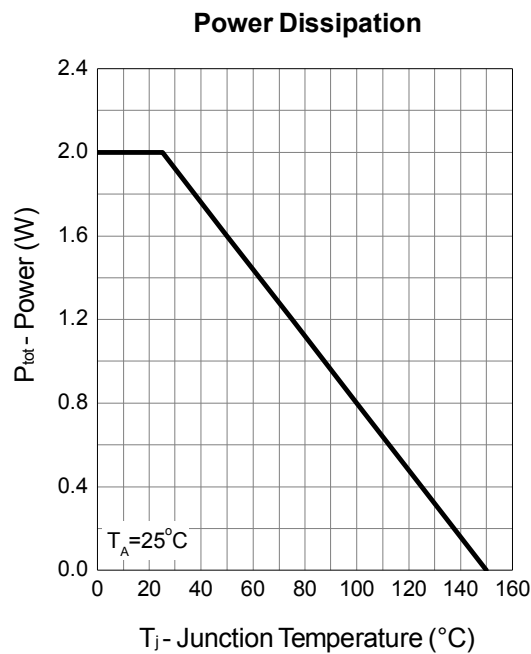
Symbol	Parameter	Test Conditions	P Channel			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =-250μA	-30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-24V, V _{GS} =0V	-	-	-1	μA
		T _J =85°C	-	-	-30	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =-250μA	-1.2	-1.7	-2.2	V
I _{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
R _{DS(ON)} ^e	Drain-Source On-state Resistance	V _{GS} =-10V, I _{DS} =-4A	-	37	48	mΩ
		V _{GS} =-4.5V, I _{DS} =-3A	-	55	72	
Diode Characteristics						
V _{SD} ^e	Diode Forward Voltage	I _{DS} =-1.2A, V _{GS} =0V	-	-0.8	-1	V
t _{rr}	Reverse Recovery Time	I _{SD} =-4A, dI _{SD} /dt=100A/μs	-	14	-	ns
Q _{rr}	Reverse Recovery Charge		-	8	-	nC
Dynamic Characteristics ^f						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz	-	3.4	-	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-15V, Frequency=1.0MHz	-	580	-	pF
C _{oss}	Output Capacitance		-	105	-	
C _{rss}	Reverse Transfer Capacitance		-	80	-	
t _{d(ON)}	Turn-on Delay Time	V _{DD} =-15V, R _L =15Ω, I _{DS} =-1A, V _{GEN} =-4.5V, R _G =1Ω	-	9	-	ns
t _r	Turn-on Rise Time		-	11	-	
t _{d(OFF)}	Turn-off Delay Time		-	23	-	
t _f	Turn-off Fall Time		-	11	-	
Gate Charge Characteristics ^f						
Q _g	Total Gate Charge	V _{DS} =-15V, V _{GS} =-4.5V, I _{DS} =-4A	-	6.7	-	nC
Q _g	Total Gate Charge	V _{DS} =-15V, V _{GS} =-10V, I _{DS} =-4A	-	13.5	-	
Q _{gs}	Gate-Source Charge		-	2	-	
Q _{gd}	Gate-Drain Charge		-	2.9	-	
Q _{gth}	Threshold Gate Charge		-	1	-	

Note e Pulse test; pulse width≤300μs, duty cycle≤2%.

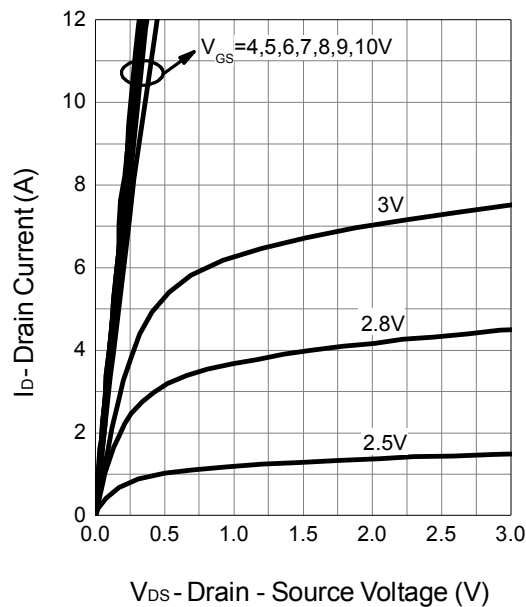
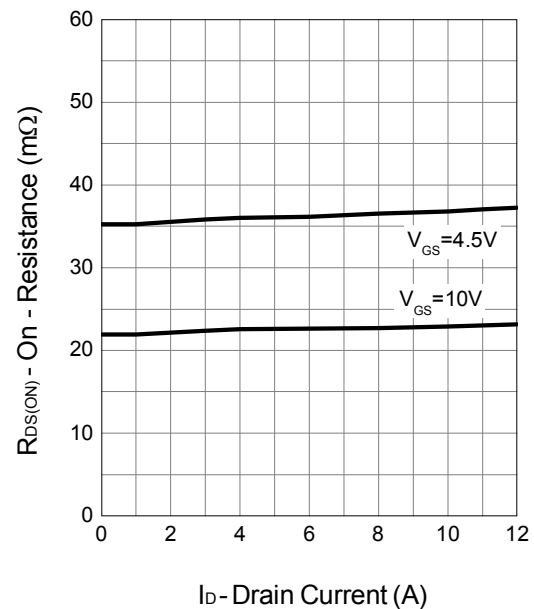
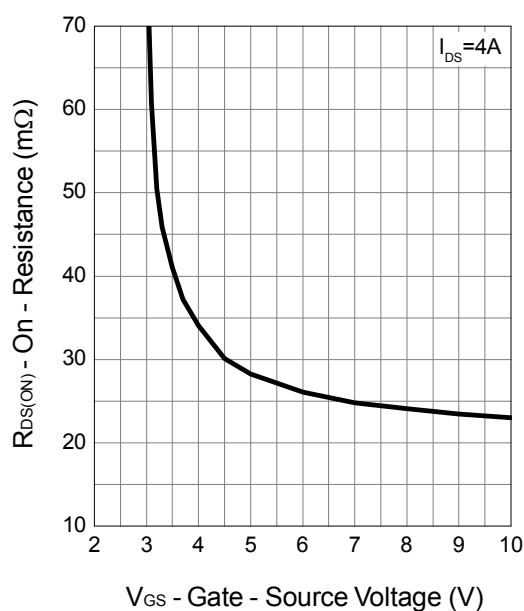
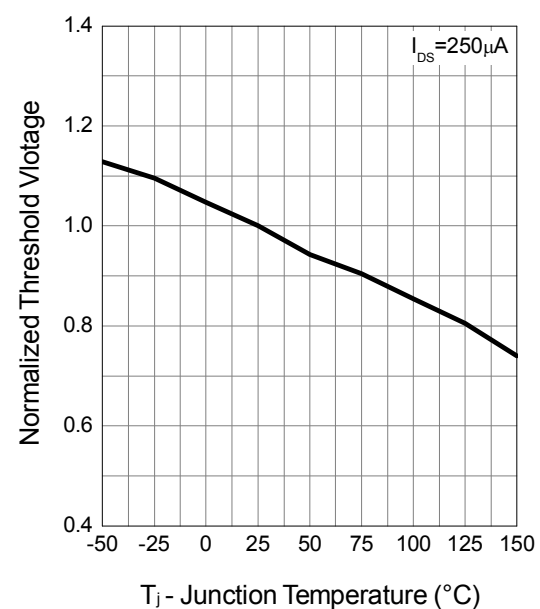
Note f : Guaranteed by design, not subject to production testing.

:

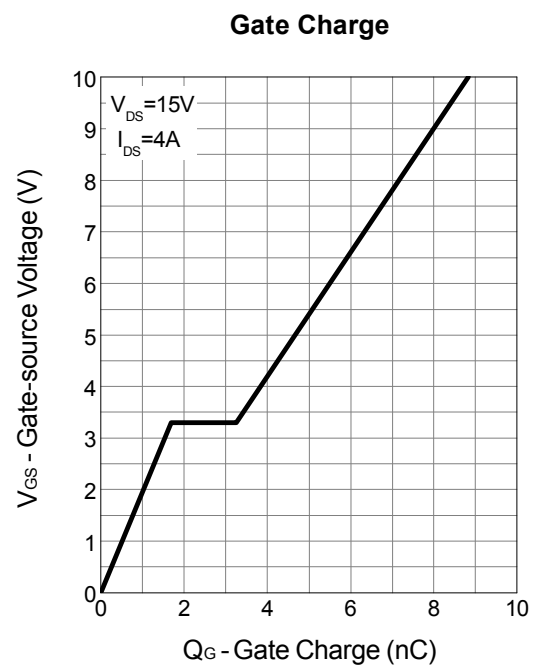
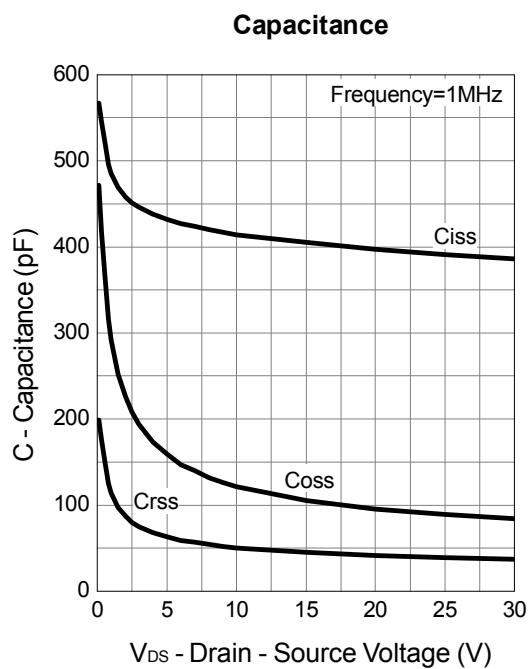
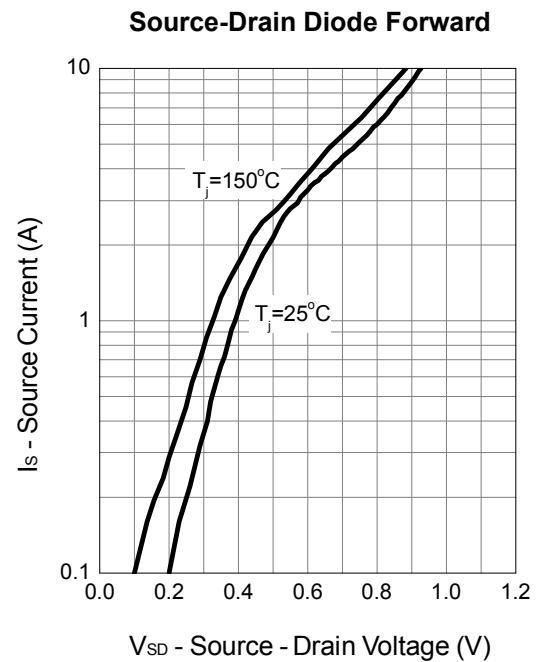
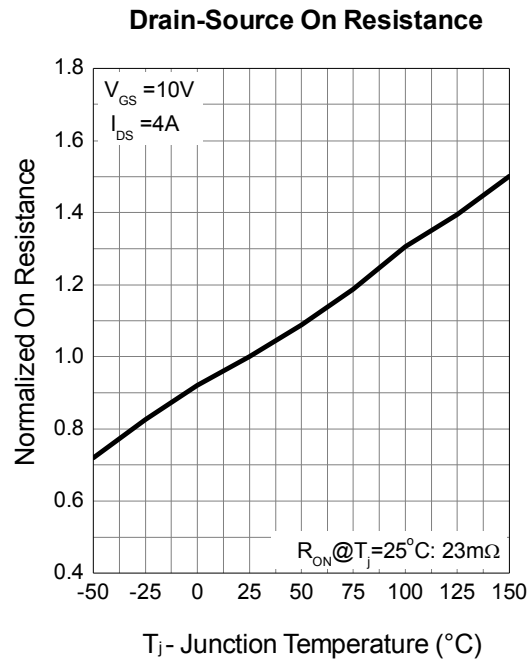
N Channel Typical Operating Characteristics



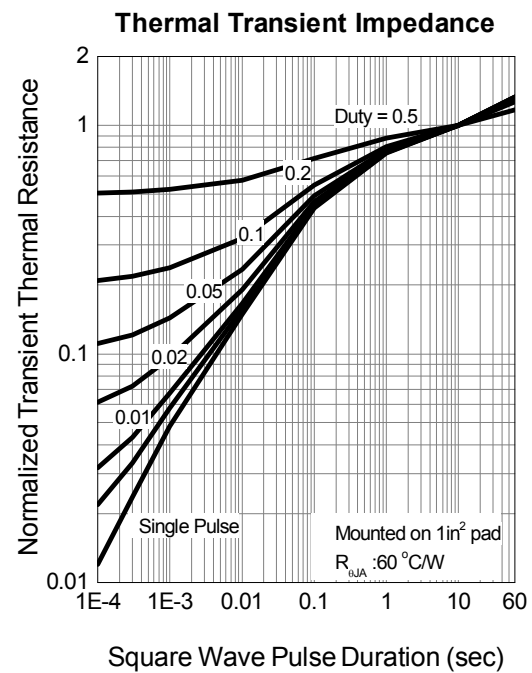
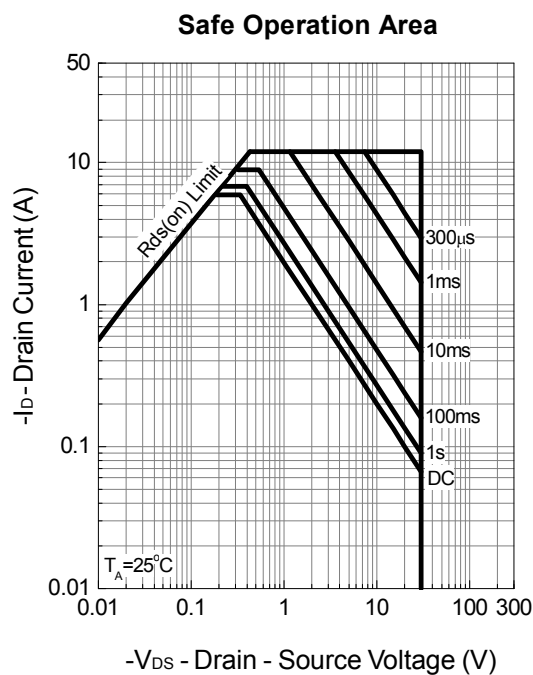
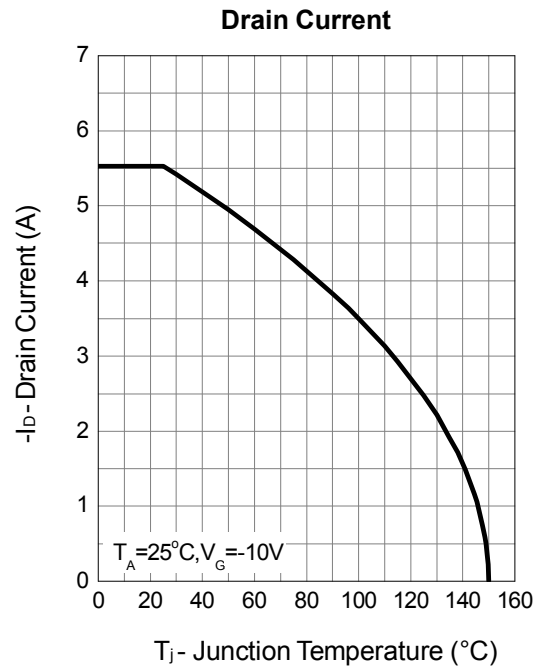
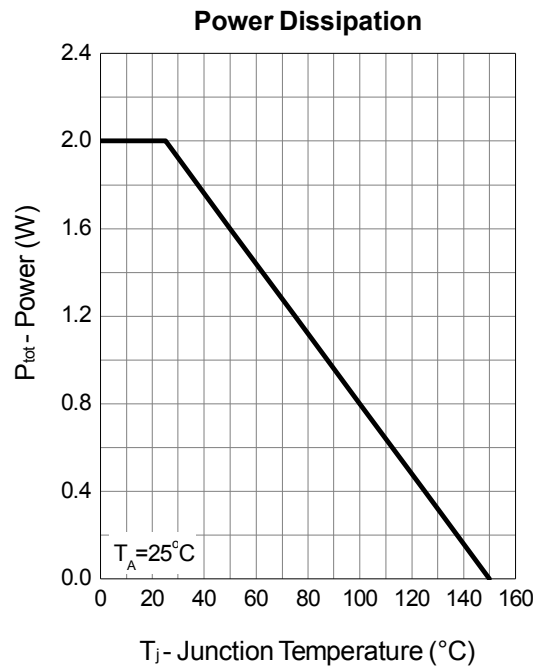
N Channel Typical Operating Characteristics (Cont.)

Output Characteristics

Drain-Source On Resistance

Gate-Source On Resistance

Gate Threshold Voltage


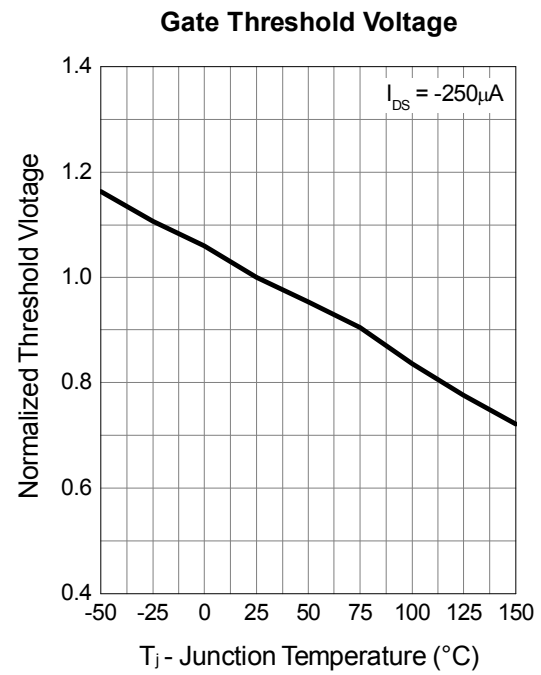
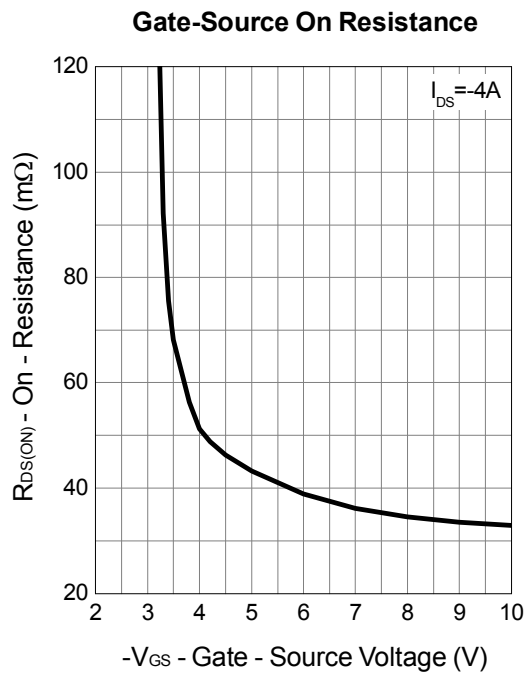
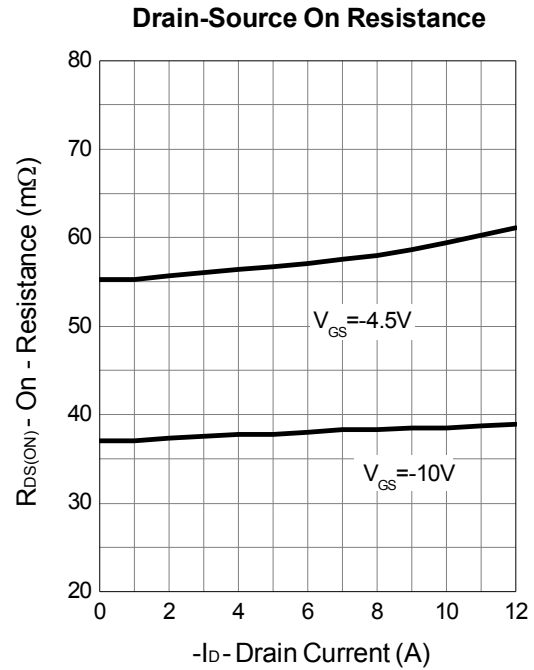
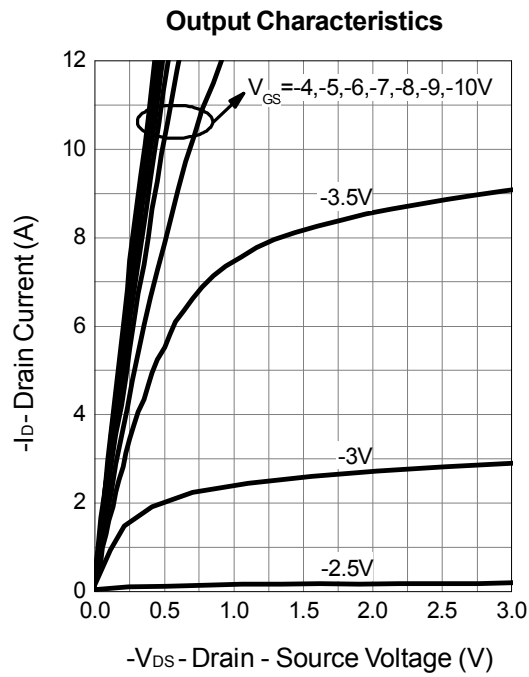
N Channel Typical Operating Characteristics (Cont.)



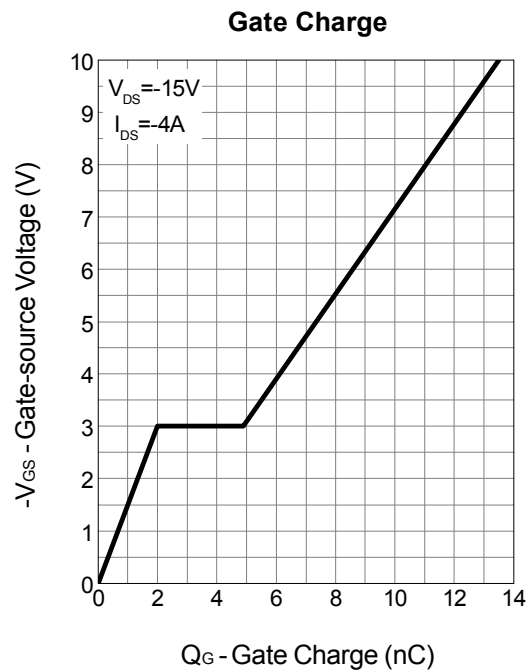
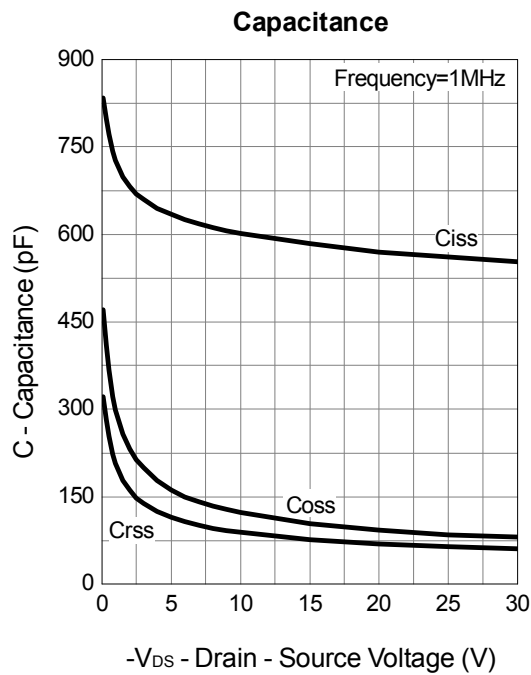
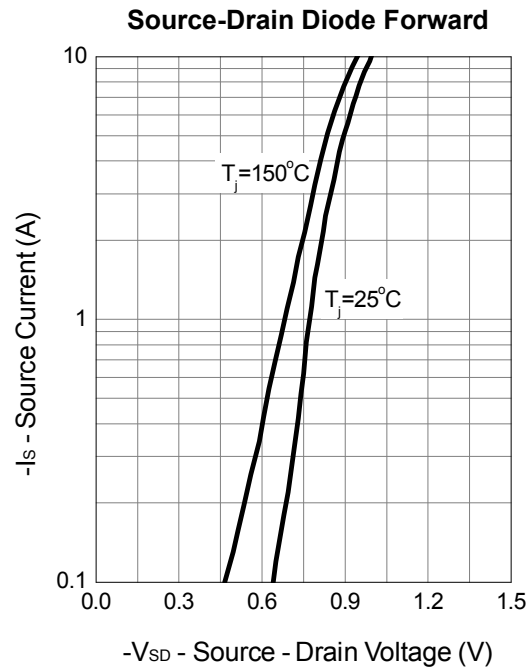
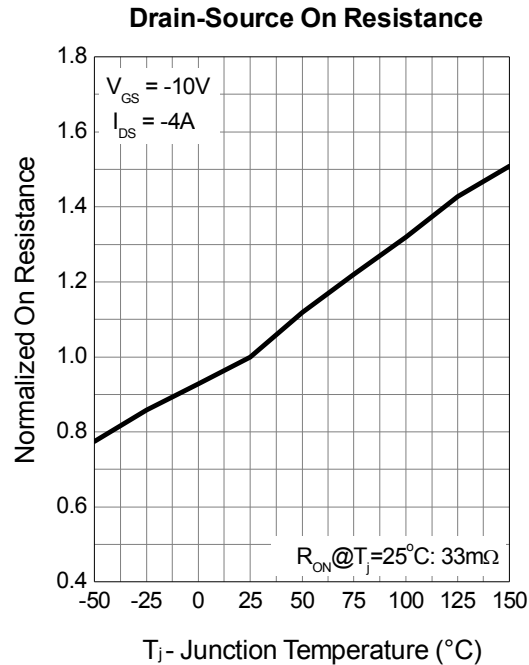
P Channel Typical Operating Characteristics



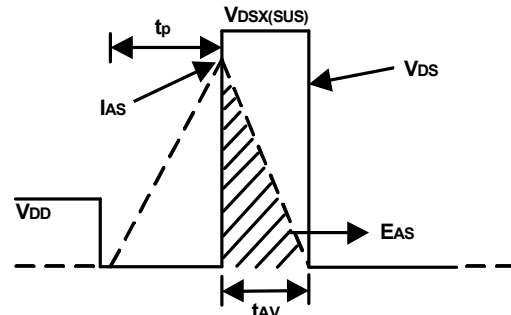
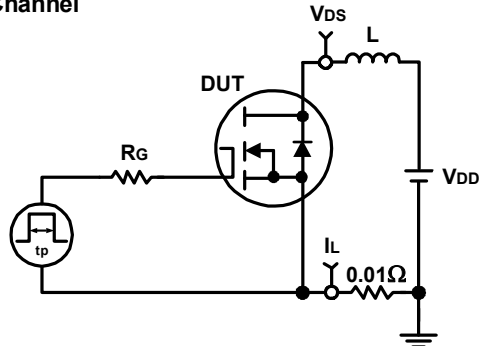
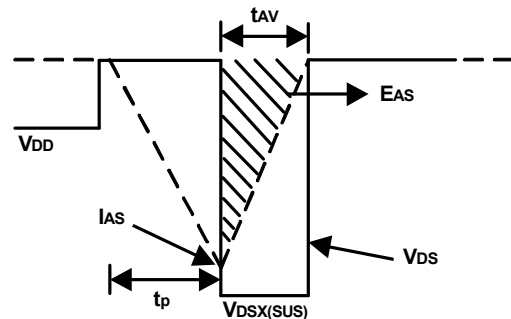
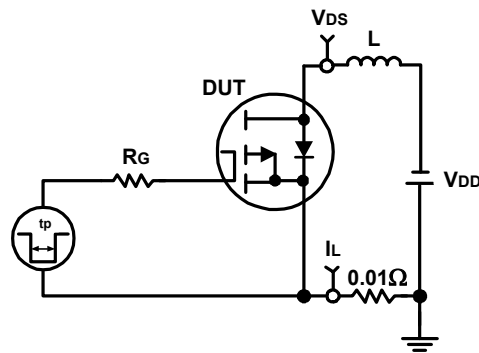
P Channel Typical Operating Characteristics (Cont.)



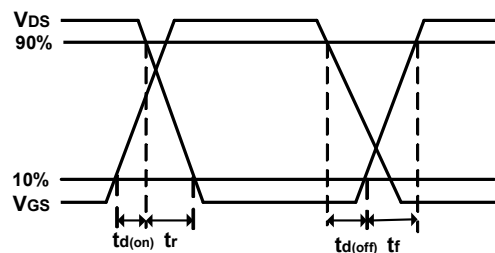
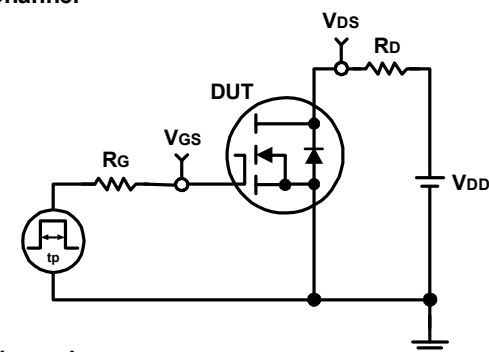
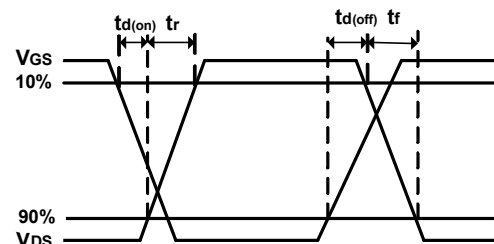
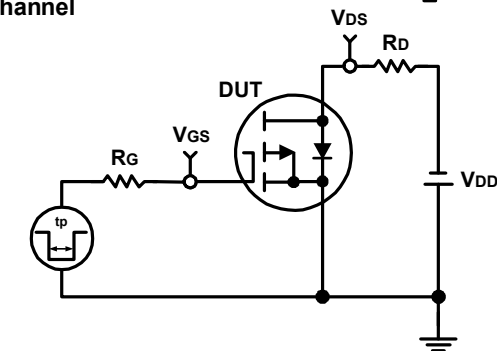
P Channel Typical Operating Characteristics (Cont.)



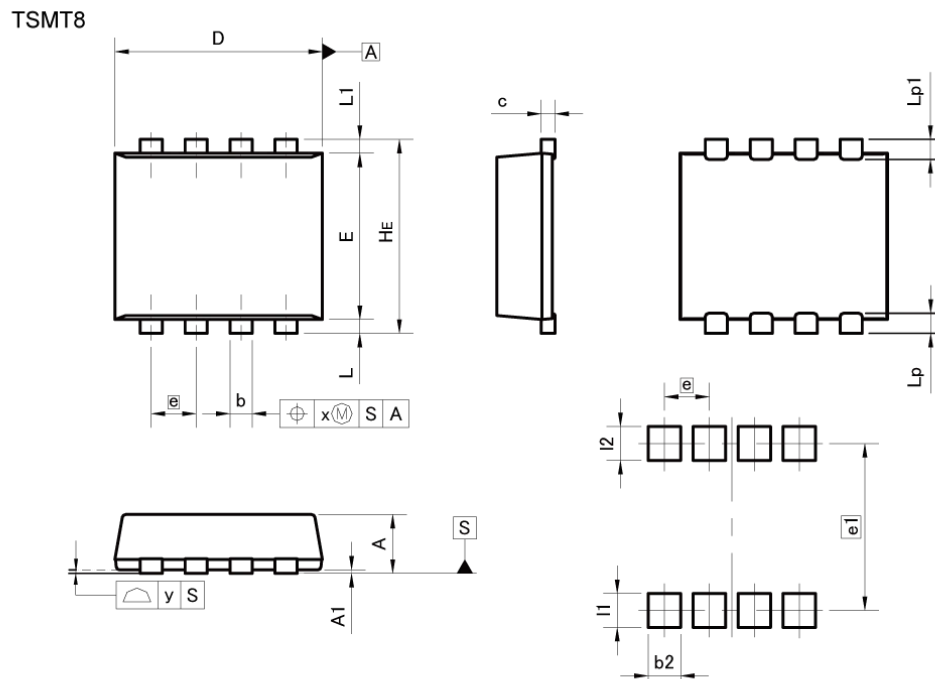
Avalanche Test Circuit and Waveforms

N Channel

P Channel


Switching Time Test Circuit and Waveforms

N Channel

P Channel


●Dimensions



Pattern of terminal position areas
[Not a pattern of soldering pads]

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.75	0.85	0.030	0.033
A1	0.00	0.05	0.000	0.002
b	0.27	0.37	0.011	0.015
c	0.12	0.22	0.005	0.009
D	2.90	3.10	0.114	0.122
E	2.30	2.50	0.091	0.098
e	0.65		0.026	
HE	2.70	2.90	0.106	0.114
L	0.10	0.30	0.004	0.012
L1	0.10	0.30	0.004	0.012
Lp	0.19	0.39	0.007	0.015
Lp1	0.19	0.39	0.007	0.015
x	—	0.10	—	0.004
y	—	0.10	—	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	—	0.47	—	0.019
e1	2.41		0.095	
l1	—	0.49	—	0.019
l2	—	0.49	—	0.019

Dimension in mm/inches